Electronic Patent Application Fee Transmittal							
Application Number:	10565587						
Filing Date:	22-Feb-2007						
Title of Invention:	Copper Foil with Ultra Thin Adhesive Layer, and a Method for Manufacturing the Copper Foil with Ultra Thin Adhesive Layer						
First Named Inventor/Applicant Name:	Tetsuro Sato						
Filer:	Sean Christophe Myers-Payne/Sonja Combest						
Attorney Docket Number:	3209-111						
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Filing	Fees						
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:	·						
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Petition: Patent-Appeals-and-Interference:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
	Total in USD (\$)			810